



Parameters	Ratings	Units
Peak Blocking Voltage	350	V _P
Load Current	130	mA _{rms} / mA _{DC}
On-Resistance (max)	30	Ω
Isolation Voltage, Input to Output	5000	V _{rms}

Features

- 5000V_{rms} Input/Output Isolation
- 350V_P Blocking Voltage
- 100% Solid State
- Low Drive Power Requirements (TTL/CMOS Compatible)
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 4-Pin Package
- Machine Insertable, Wave Solderable

Applications

- Telephony Switching
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

The CPC1333G is a single-pole, normally closed (1-Form-B) Solid State Relay with an enhanced input to output isolation barrier of $5000V_{rms}$.

The relay output is constructed with efficient MOSFET switches that use IXYS Integrated Circuits Division's patented OptoMOS architecture. The input, a highly efficient GaAIAS infrared LED, controls the optically coupled output.

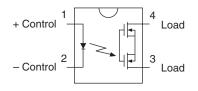
Approvals

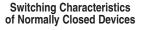
- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1172007
- Certified to EN 60950-1: 2006 TUV Certificate B 09 07 49410 004

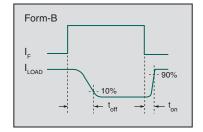
Ordering Information

Part Number	Description
CPC1333G	4-Pin DIP (100/Tube)
CPC1333GR	4-Pin Surface Mount (100/Tube)
CPC1333GRTR	4-Pin Surface Mount (1000/Reel)

Pin Configuration











Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Peak Blocking Voltage	350	V _P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	А
Input Power Dissipation ¹	100	mW
Total Package Dissipation ²	550	mW
Isolation Voltage, Input to Output	5000	V _{rms}
ESD Rating, Human Body Model	8	kV
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C
Maximum Soldering Temperature (10 Seconds)	260	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

¹ Derate linearly 1.33 mW / °C ² Derate linearly 3.00 mW / °C

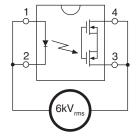
Electrical Characteristics @ 25°C

Parameters	Conditions	Symbol	Min	Тур	Max	Units
Output Characteristics						
Load Current						
Continuous	-	۱	-	-	130	mA _{rms} / mA _{DC}
Peak	t=10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance ¹	I _L =130mA	R _{ON}	-	25	30	Ω
Off-State Leakage Current	I _F =2mA, V _L =350V	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	$L = m \Lambda V = 10 V$	t _{on}	-	-	2	
Turn-Off	I _F =5mA, V _L =10V	t _{off}	-	-	3	- ms
Output Capacitance	I _F =2mA, V _L =50V, f=1MHz	C _{OUT}	-	6	-	pF
Input Characteristics					1	1
Input Control Current to Activate ²	-	I _F	-	0.18	2	mA
Input Control Current to Deactivate	I _L =130mA	I _F	0.1	-	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.26	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Common Characteristics		· 1				
Input to Output Capacitance	-	C _{I/O}	-	3	-	pF

¹ Measurement taken within one second of on-time.

² For high temperature operation (> 60°C), IXYS Integrated Circuits Division recommends a LED $I_F \ge 5mA$.

CPC1333G Isolation Test Circuit

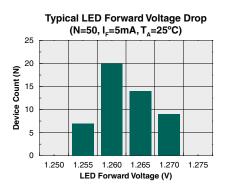


Test Conditions: Voltage Ramp: Test Time: Leakage Current Threshold: Test Voltage:

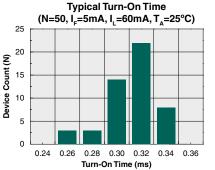
2V/μs 2 Seconds 50μΑ 6kV_{rms}

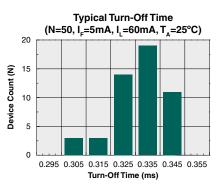


CPC1333



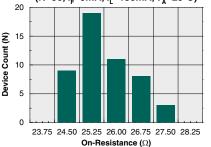
PERFORMANCE DATA*



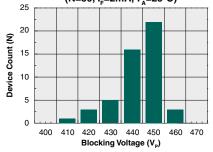


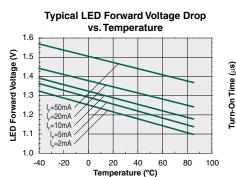
Typical I₂ for Switch Operation (N=50, I, =130mA, T_=25°C) 25 20 Device Count (N) 15 10 5 0 0.20 0.12 0.14 0.16 0.18 0.22 LED Current (mA)

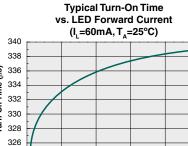
Typical On-Resistance Distribution (N=50, I_F=0mA, I_L=130mA, T_A=25°C)



Typical Blocking Voltage Distribution (N=50, I_F=2mA, T_a=25°C)







20

LED Current (mA)

30

40

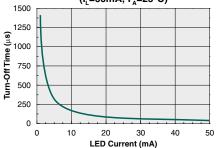
50

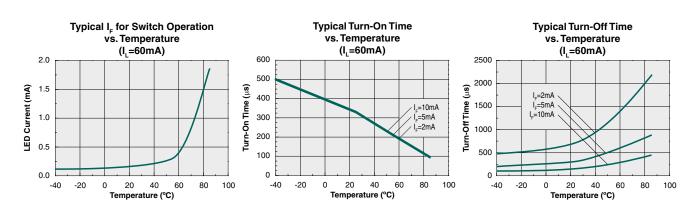
324

0

10

Typical Turn-Off Time vs. LED Forward Current (I, =60mA, T₄=25°C)





* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

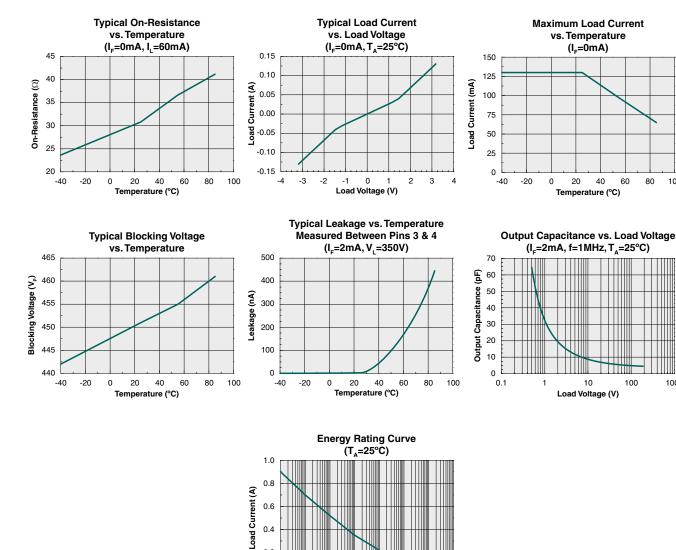


60 80 100

100

1000

PERFORMANCE DATA*



0.2 0.0

10µs 100µs 1ms

* The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

10ms 100ms

Time

1s 10s 100s



Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
CPC1333G / CPC1333GR	MSL 1

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
CPC1333G / CPC1333GR	250°C for 30 seconds

Board Wash

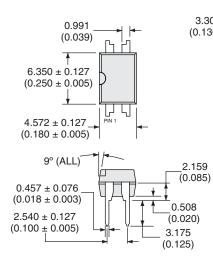
IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

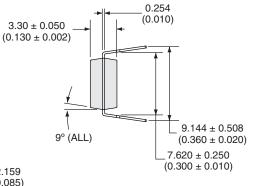




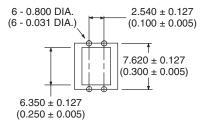
Mechanical Dimensions

CPC1333G



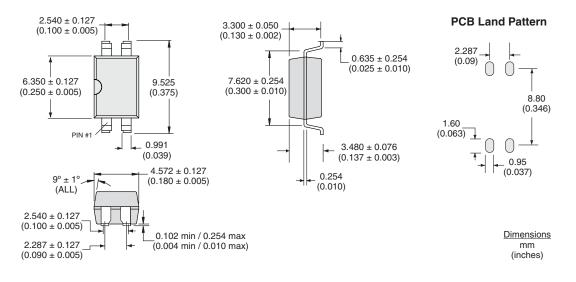


PC Board Pattern (Top View)



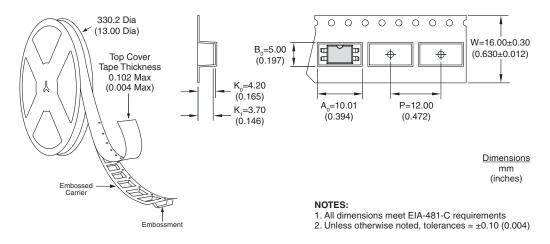
Dimensions mm (inches)

CPC1333GR





CPC1333GRTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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